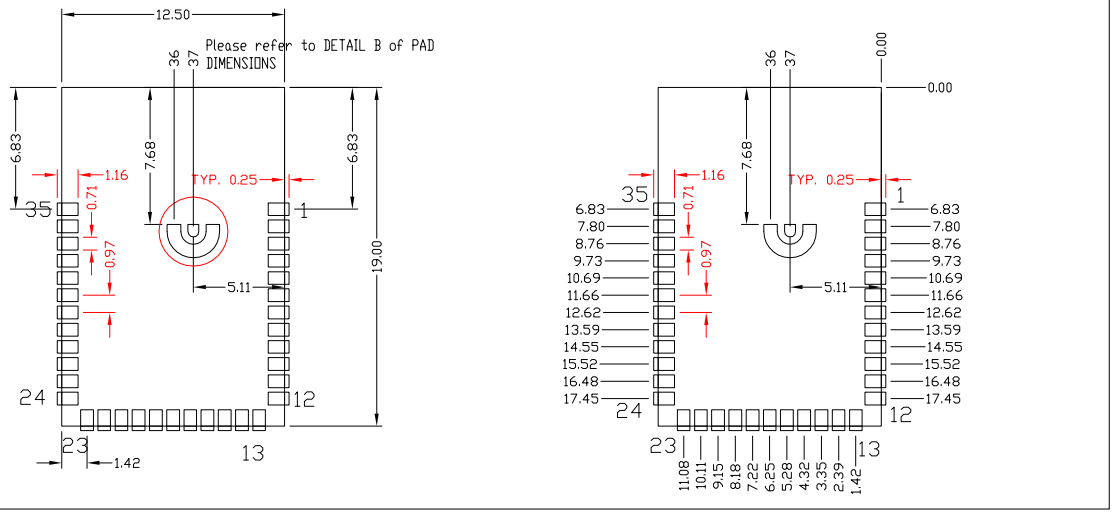
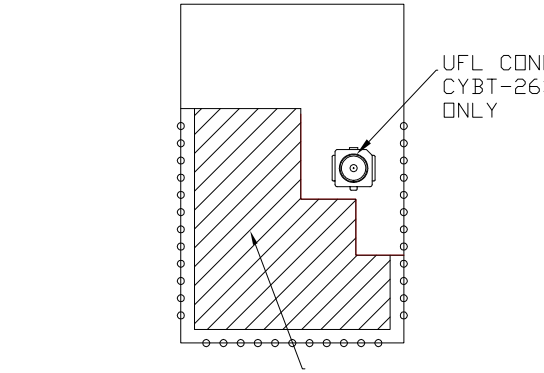
RECOMMEND PCB PATTERN



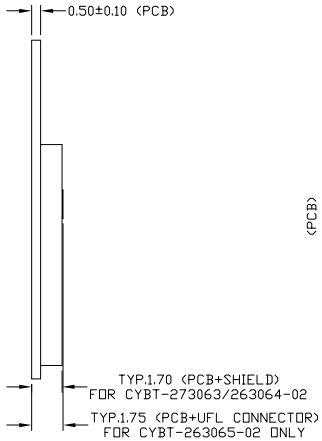
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
0.1	INITIAL RELEASE	WW1936	
0.2	CHANGE WIDTH OF PCB AND SHIELD	WW1952	

MODULE PAD ASSIGNMENT:

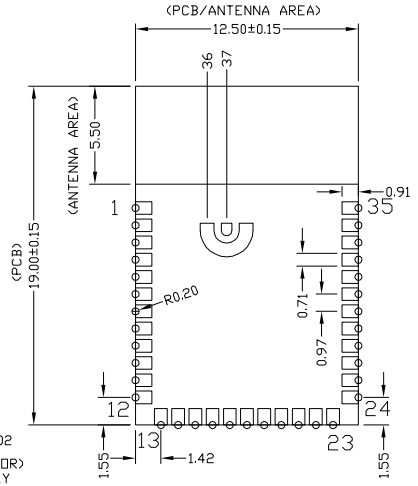
PAD1:GND	PAD21:XTALO_32K
PAD2:XRES	PAD22:GND
PAD3:P29	PAD23:P3
PAD4:P26	PAD24:P8
PAD5:P37	PAD25:P15
PAD6:P1	PAD26:P4
PAD7:P0	PAD27:P28
PAD8:P10	PAD28:UART_CTS_N
PAD9:P11	PAD29:HOST_WAKE
PAD10:P13	PAD30:UART_RXD
PAD11:P14	PAD31:UART_TXD
PAD12:P12	PAD32:DEV_WAKE
PAD13:GND	PAD33:UART_RTS_N
PAD14:P9	PAD34:VDD
PAD15:P17	PAD35:GND
PAD16:P5	PAD36:GDN-for 263064 only
PAD17:P6	PAD37:ANT-for 263064 only
PAD18:P2	
PAD19:GND	
PAD20:XTALI_32K	



SEEN FROM TOP



SEEN FROM SIDE



SEEN FROM BOTTOM

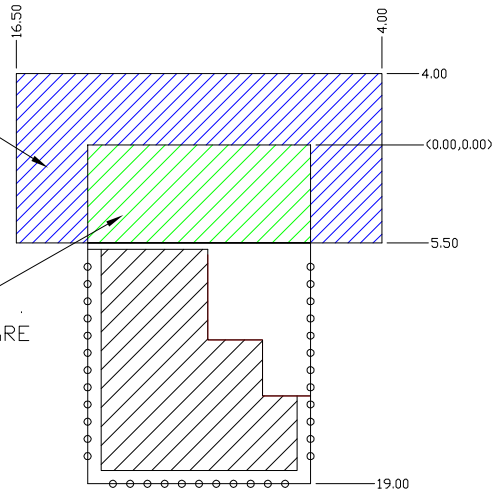


SCALE 1:1

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	CYPRESS SEMICONDUCTOR Corp.
DIMENSIONS ARE IN MM TOLERANCES ON: +/- 0.15 MM ANGLES +/-0.5 DEGREE	DRAWN:	WW1952	CYBT-273063/263064/263065-02
	CHECKED		
	ENGRG		
	ISSUED		
			SIZE: — REV NO: 0.2 — DWG NO:
			SCALE 5:1 — THE 3RD PROJECTION — SHEET: 1 OF 1

HOST PCB KEEP OUT AREA AROUND ANTENNA

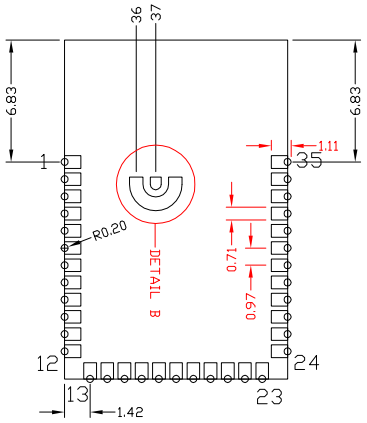
1. FOR BEST RF PERFORMANCE,ADDITIONAL KEEPOUT IN BLUE HATCHED AREA ON THE HOST BOARD ON ALL LAYERS.
2. RECOMMENDATION IS TO PLACE THE BLE MODULE IN THE CORNER OF THE HOST BOARD.
3. FOR CYBT-273063-02 ONLY

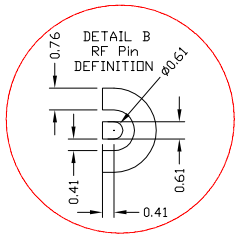


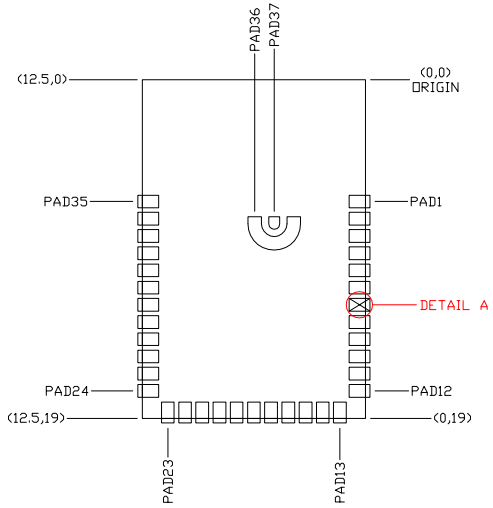
SOLDER PAD AND LOCATION

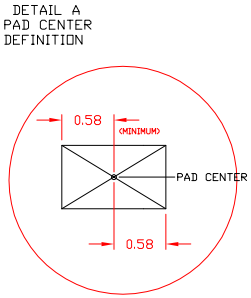
Solder Pad (Center of Pad)	Location (X,Y) from Origin (mm)	Dimension from Origin (mil)
1	(0.33, 6.83)	(12.99, 268.90)
2	(0.33, 7.80)	(12.99, 307.09)
3	(0.33, 8.76)	(12.99, 344.88)
4	(0.33, 9.73)	(12.99, 383.07)
5	(0.33, 10.69)	(12.99, 420.87)
6	(0.33, 11.66)	(12.99, 459.05)
7	(0.33, 12.62)	(12.99, 496.85)
8	(0.33, 13.59)	(12.99, 535.04)
9	(0.33, 14.55)	(12.99, 572.83)
10	(0.33, 15.52)	(12.99, 611.02)
11	(0.33, 16.48)	(12.99, 648.82)
12	(0.33, 17.45)	(12.99, 687.01)
13	(1.42, 18.67)	(55.91, 735.04)
14	(2.39, 18.67)	(94.09, 735.04)
15	(3.35, 18.67)	(131.89, 735.04)
16	(4.32, 18.67)	(170.08, 735.04)
17	(5.28, 18.67)	(207.87, 735.04)
18	(6.25, 18.67)	(246.06, 735.04)
19	(7.22, 18.67)	(284.25, 735.04)
20	(8.18, 18.67)	(322.05, 735.04)
21	(9.15, 18.67)	(360.24, 735.04)
22	(10.11, 18.67)	(398.03, 735.04)
23	(11.08, 18.67)	(436.22, 735.04)
24	(12.17, 17.45)	(479.13, 687.01)
25	(12.17, 16.48)	(479.13, 648.82)
26	(12.17, 15.52)	(479.13, 611.02)
27	(12.17, 14.55)	(479.13, 572.83)
28	(12.17, 13.59)	(479.13, 535.04)
29	(12.17, 12.62)	(479.13, 496.85)
30	(12.17, 11.66)	(479.13, 459.05)
31	(12.17, 10.69)	(479.13, 420.87)
32	(12.17, 9.73)	(479.13, 383.07)
33	(12.17, 8.76)	(479.13, 344.88)
34	(12.17, 7.80)	(479.13, 307.09)
35	(12.17, 6.83)	(479.13, 268.90)

PAD DIMENSION









UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	CYPRESS SEMICONDUCTOR Corp.
DIMENSIONS ARE IN MM TOLERANCES ON: +/- 0.20 MM	DRAWN:	WW1952	
	CHECKED		
	ENGRG		
ANGLES +/-0.5 DEGREE	ISSUED		CYBT-273063/263064/263065-02
			SIZE: — REV NO: 0.2 — DWG NO:
			SCALE 5:1 — THE 3RD PROJECTION — SHEET: 2 OF 2